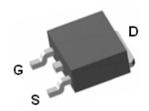




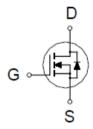
### **N-Channel Enhancement Mode MOSFET**

#### **PRODUCT SUMMARY**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub>
30V	$9m\Omega @V_{GS} = 10V$	57A



**TO-252** 



#### **ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C Unless Otherwise Noted)**

ABOOLOTE MAXIMOM RATINGO (TA = 20° 0 offices office wise rolled)							
PARAMETERS/TEST CO	SYMBOL	LIMITS	UNITS				
Drain-Source Voltage	$V_{DS}$	V <sub>DS</sub> 30					
Gate-Source Voltage	$V_{GS}$	±20	V				
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	57				
Continuous Diam Current	T <sub>C</sub> = 100 °C	I <sub>D</sub>	37	A			
Pulsed Drain Current <sup>1</sup>	I <sub>DM</sub> 150		^				
Avalanche Current	I <sub>AS</sub>	29	1				
Avalanche Energy	L = 0.1mH	E <sub>AS</sub>	40	mJ			
Power Dissipation	T <sub>C</sub> = 25 °C	$P_{D}$	54	W			
rower dissipation	T <sub>C</sub> = 100 °C	i D	21				
Junction & Storage Temperature Rang	e	$T_J,T_STG$	-55 to 150	°C			

#### THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNITS
Junction-to-Case	$R_{\theta JC}$		2.3	°C / W

<sup>&</sup>lt;sup>1</sup>Pulse width limited by maximum junction temperature.





## **N-Channel Enhancement Mode MOSFET**

**ELECTRICAL CHARACTERISTICS (T<sub>1</sub> = 25 °C, Unless Otherwise Noted)** 

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			LIMITS	
PARAMETER	SYMBOL TEST CONDITIONS		MIN	TYP	MAX	UNITS	
		STATIC	-				
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30			V	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1.2	1.6	2.8	v	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			±100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 24V, V_{GS} = 0V$ $V_{DS} = 20V, V_{GS} = 0V, T_{J} = 125 \text{ °C}$			10	μΑ	
Drain-Source On-State	R <sub>DS(ON)</sub>	$V_{GS} = 4.5V, I_{D} = 20A$		11.5	18	mΩ	
Resistance <sup>1</sup>	D3(ON)	$V_{GS} = 10V, I_D = 20A$		7.5	9		
Forward Transconductance <sup>1</sup>	$g_{fs}$	$V_{DS} = 5V, I_{D} = 20A$		35		S	
		DYNAMIC					
Input Capacitance	$C_{iss}$			900		pF	
Output Capacitance	$C_{oss}$	$V_{GS} = 0V, V_{DS} = 15V, f = 1MHz$		185			
Reverse Transfer Capacitance	$C_{rss}$			120			
Gate Resistance	$R_g$	$V_{GS} = 0V$ , $V_{DS} = 0V$ , $f = 1MHz$		1.4		Ω	
Total Gate Charge <sup>2</sup>	$Q_g$	V -0.5V V -10V		22		nC	
Gate-Source Charge <sup>2</sup>	$Q_gs$	$V_{DS} = 0.5V_{(BR)DSS}, V_{GS} = 10V$ $I_{D} = 20A$		5			
Gate-Drain Charge <sup>2</sup>	$Q_gd$	1D = 20/1		6.5			
Turn-On Delay Time <sup>2</sup>	t <sub>d(on)</sub>			15			
Rise Time <sup>2</sup>	t <sub>r</sub>	$V_{DS} = 15V$ ,		25		nS	
Turn-Off Delay Time <sup>2</sup>	t <sub>d(off)</sub>	$I_D\cong 20A,\ V_{GS}=10V,\ R_{GEN}=6\Omega$		60			
Fall Time <sup>2</sup>	t <sub>f</sub>			18			
SOURCE-DR	AIN DIODE I	RATINGS AND CHARACTERISTICS (	$T_J = 25$	°C)			
Continuous Current	I <sub>S</sub>				57	Α	
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 20A, V_{GS} = 0V$			1.3	V	
Reverse Recovery Time	t <sub>rr</sub>	L = 20A dl /dt = 100A / ::\$		23		nS	
Reverse Recovery Charge	$Q_{rr}$	$I_F = 20A$ , $dI_F/dt = 100A / \mu S$		15		nC	

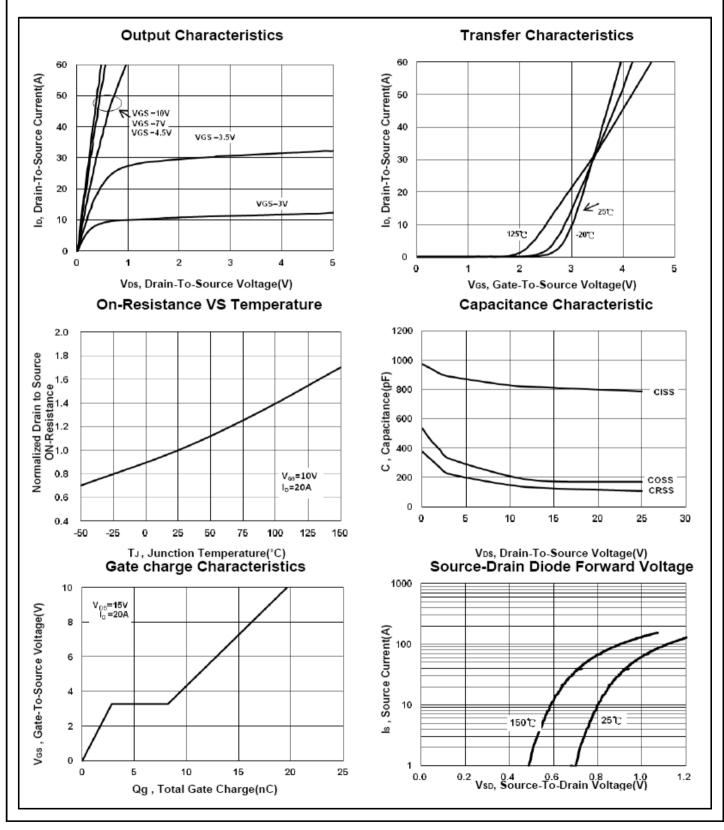
<sup>&</sup>lt;sup>1</sup>Pulse test: Pulse Width  $\leq 300 \mu sec$ , Duty Cycle  $\leq 2\%$ .

<sup>&</sup>lt;sup>2</sup>Independent of operating temperature.





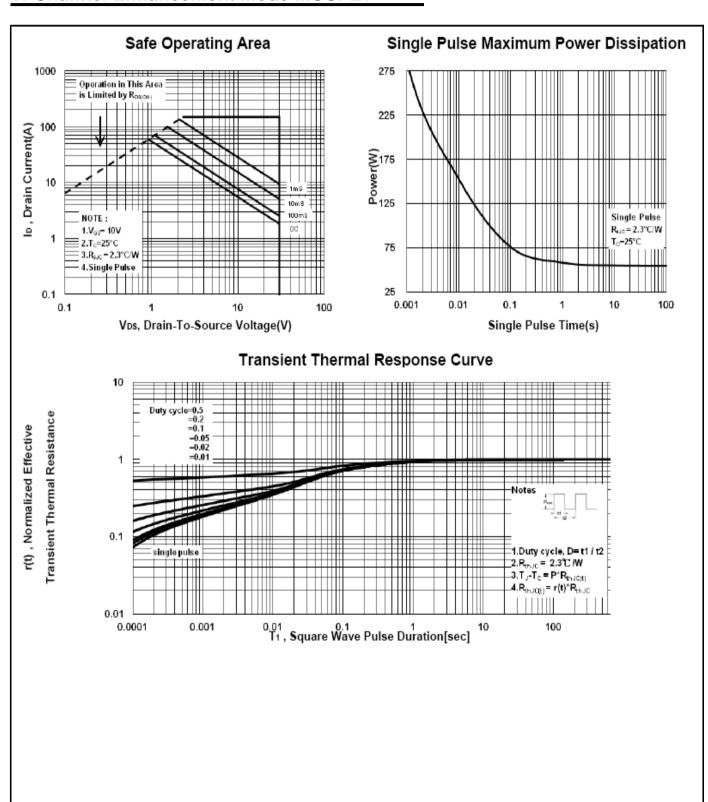
#### **N-Channel Enhancement Mode MOSFET**







#### **N-Channel Enhancement Mode MOSFET**







### **N-Channel Enhancement Mode MOSFET**

#### **Package Dimension**

# **TO-252 (DPAK) MECHANICAL DATA**

Dimension	mm				mm			
	Min.	Тур.	Max.	Dimension	Min.	Тур.	Max.	
А	8.9	10	10.41	J	4.8		5.64	
В	2.1	2.2	2.4	K	0.15		1.1	
С	0.4	0.5	0.61	L	0.4	0.76	0.89	
D	0.82	1.2	1.5	М	4.2	4.58	5	
Е	0.4	0.5	0.61	S	4.9	5.1	5.3	
F	0		0.2	Т	4.6	4.75	5.44	
G	5.3	6.1	6.3	U	1.4		1.78	
Н	0.9		1.7	V	0.55	1.25	1.7	
I	6.3	6.5	6.8					

